



Material Content Data Sheet



Sales Product Name		BSS306N H6327		Issued		1. August 2018		
MA#		MA001627296						
Package		PG-SOT23-3-5		Weight*		9.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		468	
	noble metal	gold	7440-57-5	0.017	0.18		1816	
	inorganic material	silicon	7440-21-3	0.261	2.77	3.00	27707	29991
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		320	
	non noble metal	chromium	7440-47-3	0.009	0.10		960	
	non noble metal	copper	7440-50-8	3.000	31.86	32.00	318553	319897
wire	non noble metal	copper	7440-50-8	0.073	0.77	0.77	7724	7724
encapsulation	organic material	carbon black	1333-86-4	0.056	0.60		5963	
	plastics	epoxy resin	-	1.208	12.82		128205	
	inorganic material	silicondioxide	60676-86-0	4.353	46.20	59.62	462136	596304
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15887	15887
plating	noble metal	silver	7440-22-4	0.284	3.02	3.02	30197	30197
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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